FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20740

Generic Copy

Issue Date: 04-Feb-2015

TITLE: Tape and Reel Carrier Tape Change for Die Sales

PROPOSED FIRST SHIP DATE: 11-May-2015

AFFECTED CHANGE CATEGORY(S): Change in Primary Packaging Material

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Shannon.Riggs@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <ken.fergus@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is announcing a change in carrier tape used for a selection of die sales devices as part of on-going quality improvement actions. The material change is necessary ensure proper fit of the die inside the carrier tape to provide safe transport of these devices; the change will ensure there is no unnecessary movement (rotation, die flipping) or risk of mechanical damage due to impact with the die during sealing.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Lot #	Qty OUT	100% Visual Inspection (50x magnification)	Peel Back Test	Peel Back Test After Aging Test	Visual Inspection After Aging Test (50x magnification)
A	9000	Pass. Zero die over turn / dislodge die. No damaged tape / tape jamming in T&R machine. Camber <2mm. Zero die damage at 50x mag inspection.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Zero die/bond pad oxidation out of 30 unit samples.
B	9000	Pass. Zero die over turn / dislodge die. No damaged tape / tape jamming in T&R machine. Camber <2mm. Zero die damage at 50x mag inspection.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Zero die/bond pad oxidation out of 30 unit samples.
C	8356	Pass. Zero die over turn / dislodge die. No damaged tape / tape jamming in T&R machine. Camber <2mm. Zero die damage at 50x mag inspection.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Edge with adhesive remain stick in the carrier tape. Only center of cover tape is peeled off. No die stick.	Pass. Zero die/bond pad oxidation out of 30 unit samples.

ELECTRICAL CHARACTERISTIC SUMMARY:

This is a primary packaging material change only; there are no changes to the electrical characteristics of any of the affected devices.

CHANGED PART IDENTIFICATION:

There are no changes in part identification. Date codes 2015 week 16 or later will use the new material.

Note that the implementation date code may be earlier for certain parts if customer approval is received before the FPCN expiration date. In any such cases, the implementation date code will be communicated to the customer.

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List of affected General Parts:

NCV2901CTR

List of affected Customer Specific Parts:

SZC498D27CATR
0HSBA-007-XDS
0HSBA-008-XDS
0MAFA-002-XDS